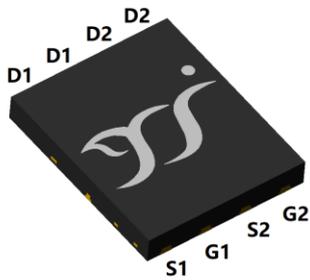
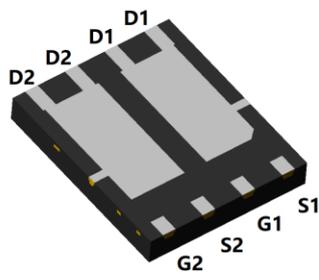


## N-Channel and P-Channel Complementary MOSFET

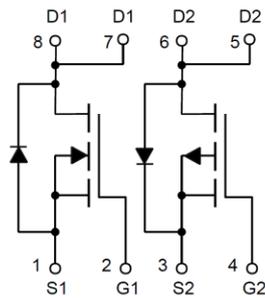


Top View



Bottom View

**DFN5060-8L**



### Product Summary NMOS

- $V_{DS}$  60V
- $I_D$  20A
- $R_{DS(ON)}$  ( at  $V_{GS}=10V$  )  $<30m\Omega$
- $R_{DS(ON)}$  ( at  $V_{GS}=4.5V$  )  $<40m\Omega$

### PMOS

- $V_{DS}$  -60V
- $I_D$  -20A
- $R_{DS(ON)}$  ( at  $V_{GS}=-10V$  )  $<45m\Omega$
- $R_{DS(ON)}$  ( at  $V_{GS}=-4.5V$  )  $<65m\Omega$

- 100% EAS Tested

### General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- Moisture Sensitivity Level 3
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

### ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	NMOS	PMOS	Unit
Drain-source Voltage		$V_{DS}$	60	-60	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	$\pm 20$	V
Drain Current	$T_A=25^\circ C$	$I_D$	4.5	-3.5	A
	$T_A=100^\circ C$		2.5	-2.2	
	$T_C=25^\circ C$		20	-20	
	$T_C=100^\circ C$		12.5	-12.5	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	50	-50	A
Avalanche energy <sup>B</sup>		EAS	30	84	mJ
Total Power Dissipation <sup>C</sup>	$T_A=25^\circ C$	$P_D$	1.6	1.7	W
	$T_A=100^\circ C$		0.6	0.7	
	$T_C=25^\circ C$		35	50	
	$T_C=100^\circ C$		14	20	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	-55~+150	$^\circ C$



# YJG20NP06A

## ■ Thermal resistance

Parameter		Symbol	NMOS		PMOS		Units
			Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient	Steady-State	$R_{\theta JA}$	60	75	55	70	°C/W
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	3	3.5	2	2.5	

## ■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG20NP06A	F1	YJG20NP06A	5000	10000	100000	13" reel

## ■ NMOS Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
		$V_{DS}=60V, V_{GS}=0V, T_J=150^\circ C$	-	-	100	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	24	30	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	-	28	40	
Diode Forward Voltage	$V_{SD}$	$I_S=20A, V_{GS}=0V$	-	0.9	1.2	V
Gate resistance	$R_G$	$f=1\text{MHz}, \text{Open drain}$	-	2.3	-	$\Omega$
Maximum Body-Diode Continuous Current	$I_S$		-	-	20	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, f=1\text{MHz}$	-	1180	-	$\mu F$
Output Capacitance	$C_{oss}$		-	70	-	
Reverse Transfer Capacitance	$C_{rss}$		-	60	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V, V_{DS}=30V, I_D=10A$	-	26	-	nC
Gate-Source Charge	$Q_{gs}$		-	5.4	-	
Gate-Drain Charge	$Q_{gd}$		-	6.5	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F=10A, di/dt=500A/\mu s$	-	12	-	nC
Reverse Recovery Time	$t_{rr}$		-	23	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=30V, I_D=10A$ $R_{GEN}=2.2\Omega$	-	10	-	ns
Turn-on Rise Time	$t_r$		-	20	-	
Turn-off Delay Time	$t_{D(off)}$		-	29	-	
Turn-off fall Time	$t_f$		-	21	-	



# YJG20NP06A

## ■ PMOS Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-60V, V_{GS}=0V$	-	-	-1	$\mu A$
		$V_{DS}=-60V, V_{GS}=0V, T_J=150^\circ\text{C}$	-	-	-100	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	-1.9	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A$	-	35	45	m $\Omega$
		$V_{GS}=-4.5V, I_D=-10A$	-	49	65	
Diode Forward Voltage	$V_{SD}$	$I_S=-20A, V_{GS}=0V$	-	-1	-1.2	V
Gate resistance	$R_G$	$f=1\text{MHz}$ , Open drain	-	12	-	$\Omega$
Maximum Body-Diode Continuous Current	$I_S$		-	-	-20	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-30V, V_{GS}=0V, f=1\text{MHz}$	-	1060	-	pF
Output Capacitance	$C_{oss}$		-	400	-	
Reverse Transfer Capacitance	$C_{rss}$		-	20	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=-10V, V_{DS}=-30V, I_D=-10A$	-	18.7	-	nC
Gate-Source Charge	$Q_{gs}$		-	4.7	-	
Gate-Drain Charge	$Q_{gd}$		-	3	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F=-10A, di/dt=100A/\mu s$	-	8	-	nC
Reverse Recovery Time	$t_{rr}$		-	20	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DD}=-30V, I_D=-10A$ $R_{GEN}=2.2\Omega$	-	7.5	-	ns
Turn-on Rise Time	$t_r$		-	40	-	
Turn-off Delay Time	$t_{D(off)}$		-	43	-	
Turn-off fall Time	$t_f$		-	55	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. NMOS:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=50V$ ,  $V_G=10V$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=11A$ .

PMOS:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-50V$ ,  $V_G=-10V$ ,  $R_G=25\Omega$ ,  $L=1\text{mH}$ ,  $I_{AS}=-13A$ .

C.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.

D. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with  $T_A=25^\circ\text{C}$ .

The maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.



# YJG20NP06A

## ■ NMOS Typical Electrical and Thermal Characteristics Diagrams

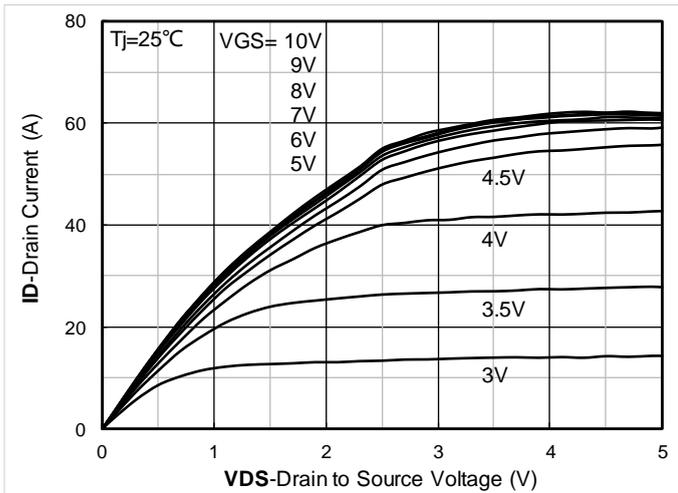


Figure 1. Output Characteristics

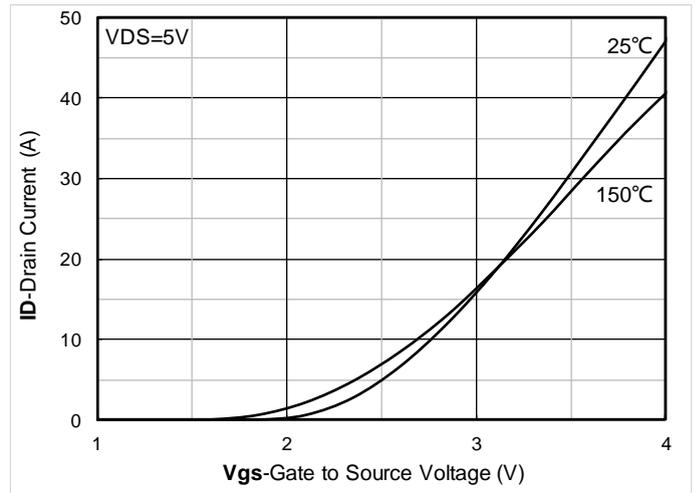


Figure 2. Transfer Characteristics

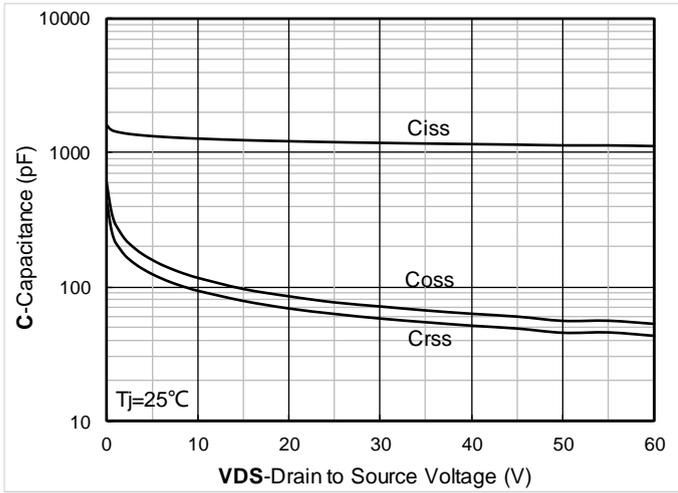


Figure 3. Capacitance Characteristics

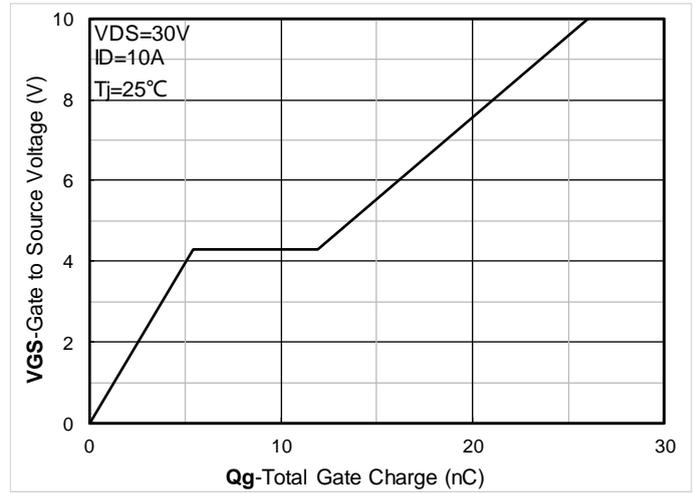


Figure 4. Gate Charge

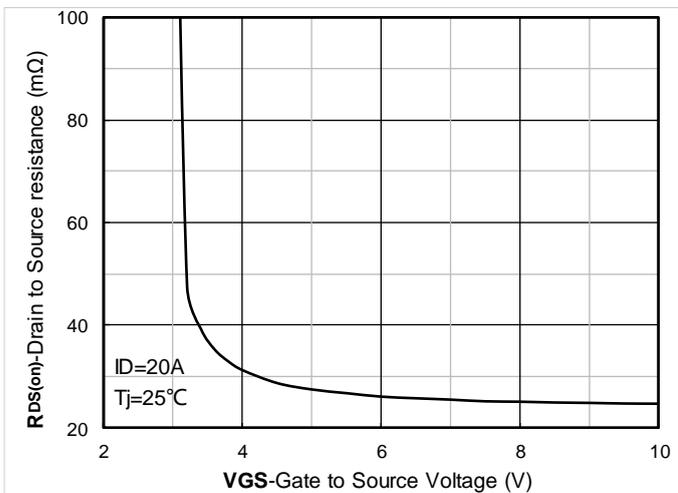


Figure 5. On-Resistance vs Gate to Source Voltage

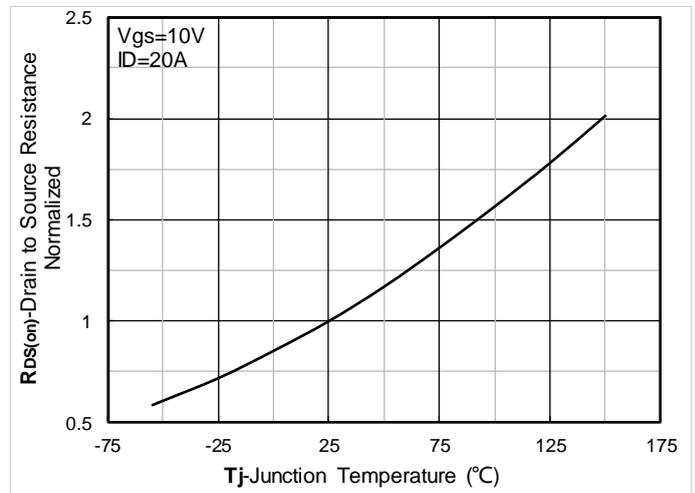


Figure 6. Normalized On-Resistance



# YJG20NP06A

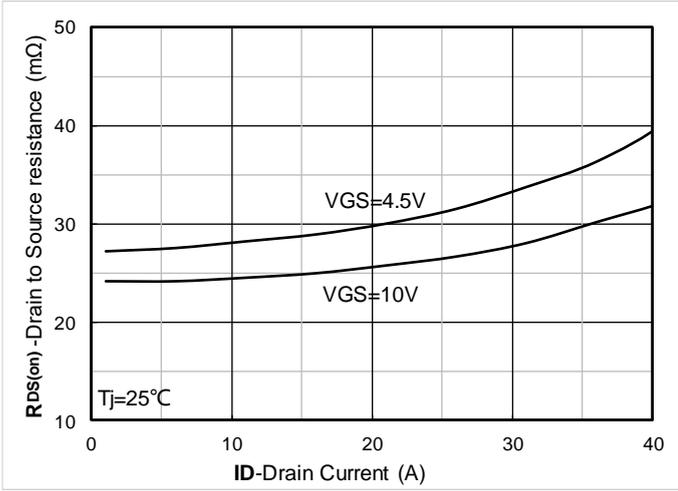


Figure 7.  $R_{DS(on)}$  VS Drain Current

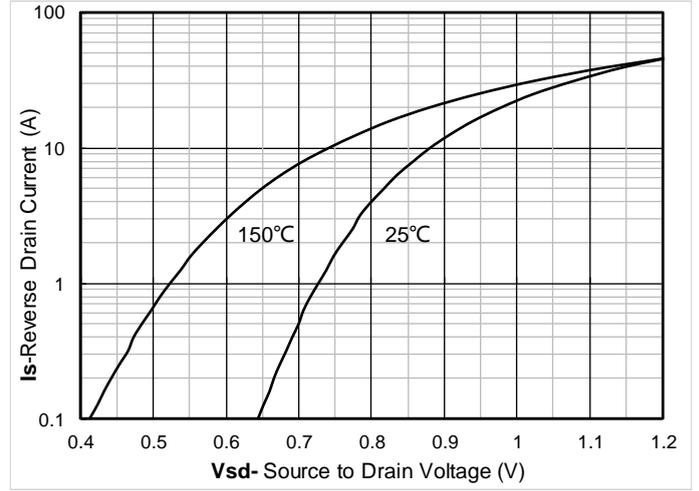


Figure 8. Forward characteristics of reverse diode

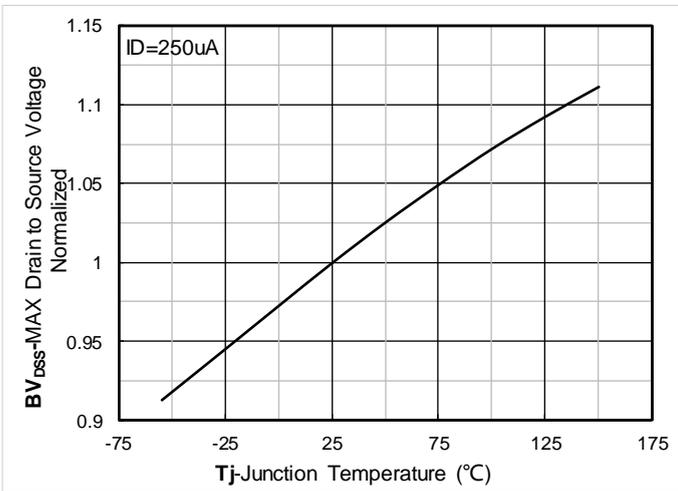


Figure 9. Normalized breakdown voltage

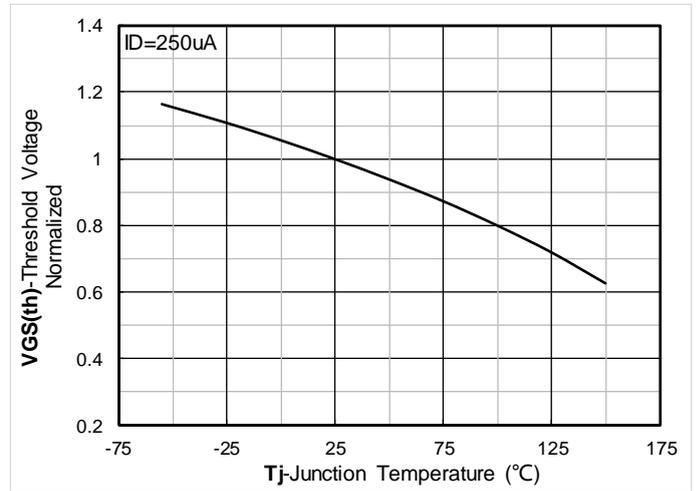


Figure 10. Normalized Threshold voltage

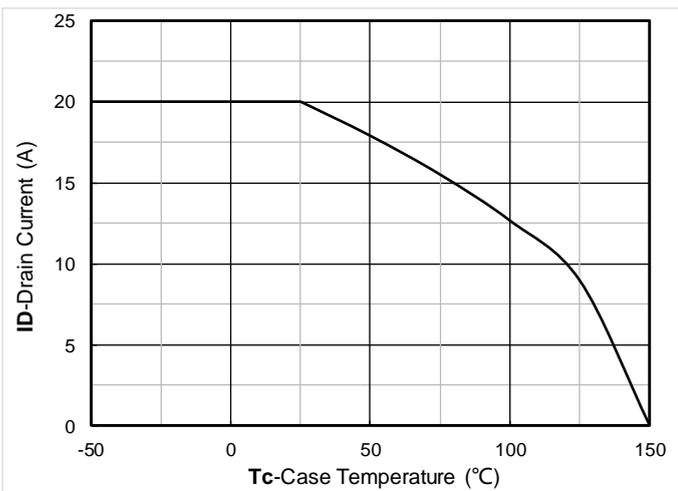


Figure 11. Current dissipation

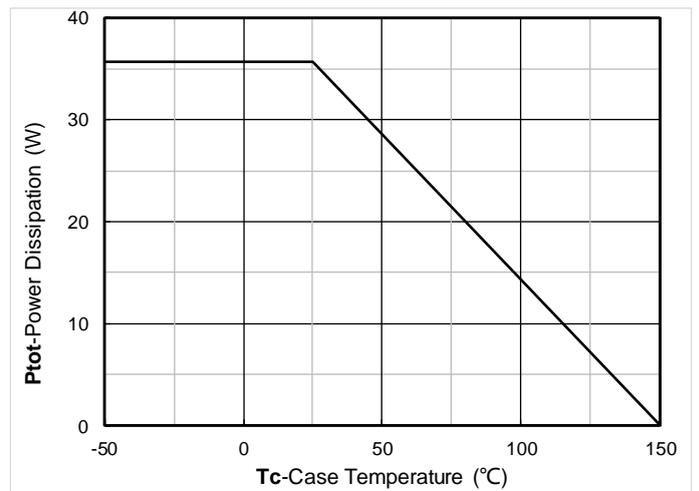


Figure 12. Power dissipation



# YJG20NP06A

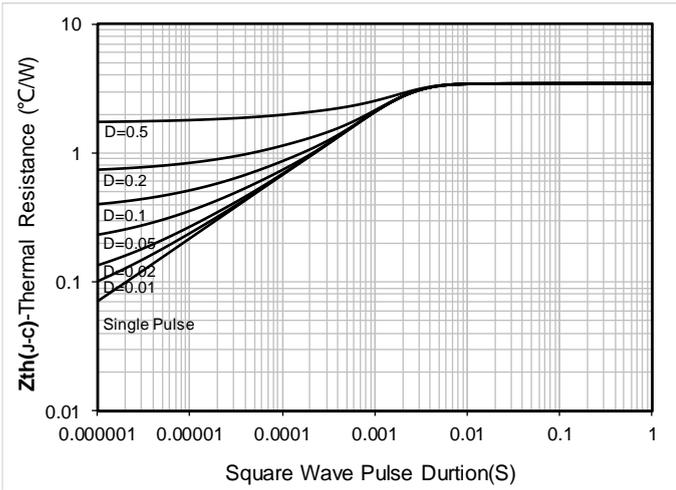


Figure 13. Maximum Transient Thermal Impedance

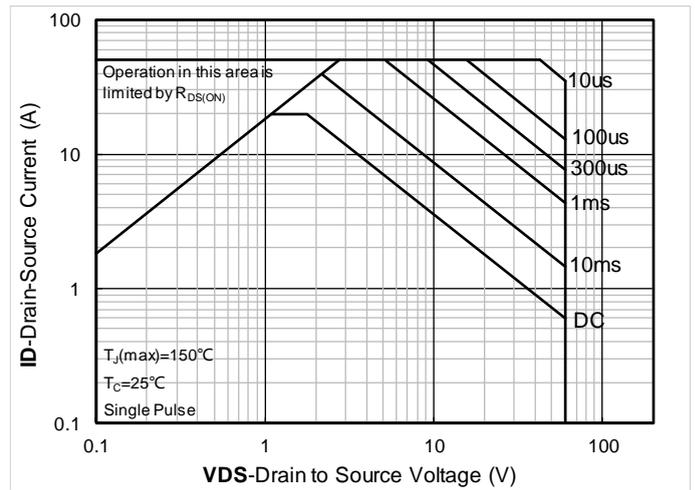


Figure 14. Safe Operation Area

## PMOS Typical Electrical and Thermal Characteristics Diagrams

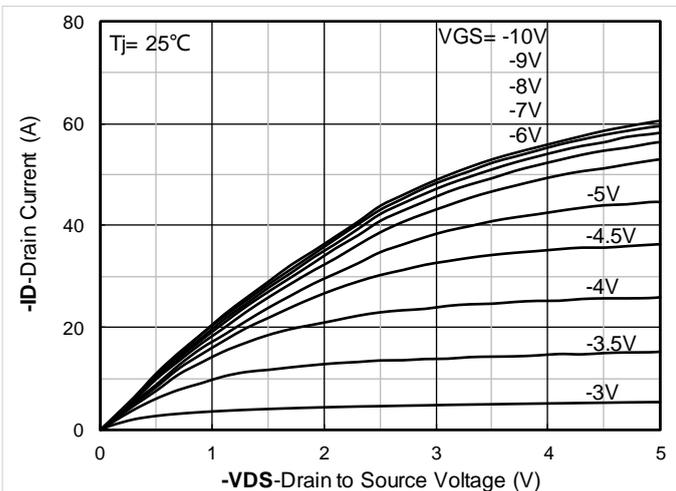


Figure 1. Output Characteristics

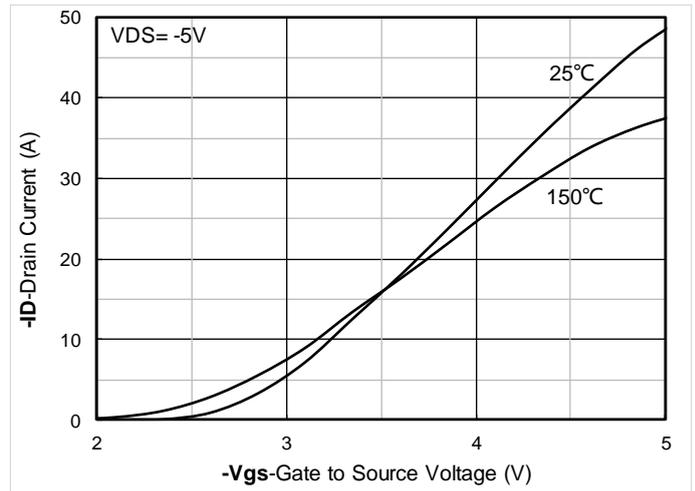


Figure 2. Transfer Characteristics

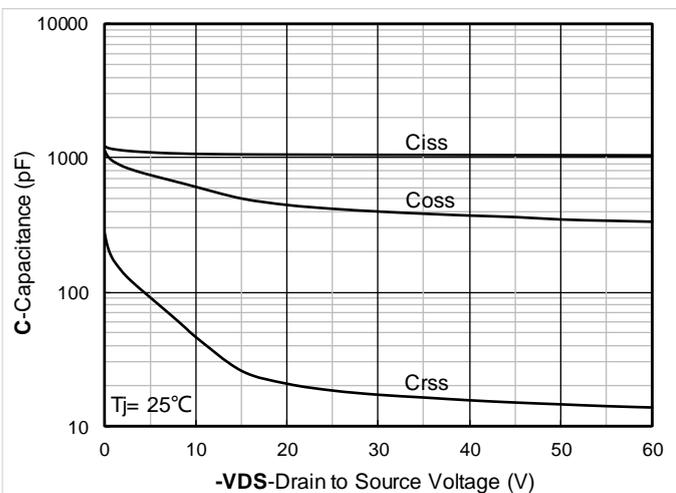


Figure 3. Capacitance Characteristics

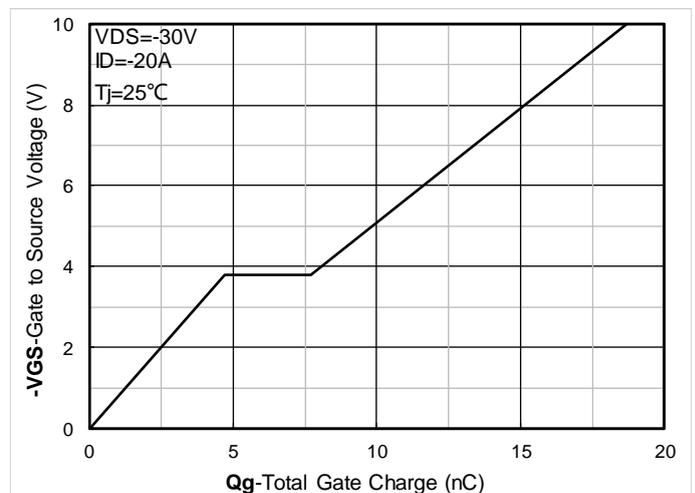


Figure 4. Gate Charge



# YJG20NP06A

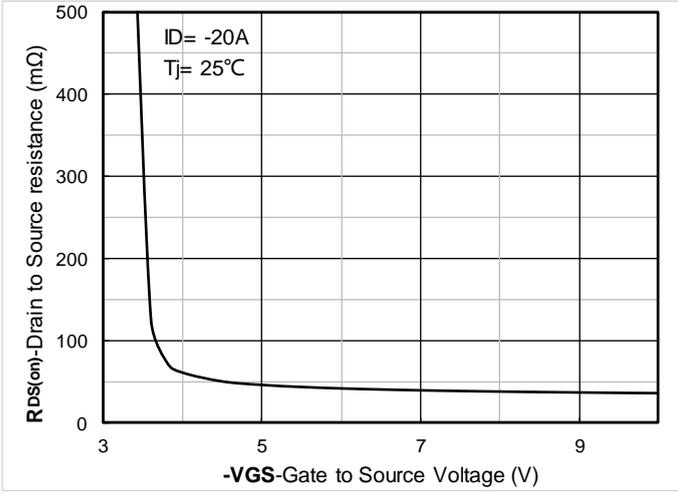


Figure 5. On-Resistance vs Gate to Source Voltage

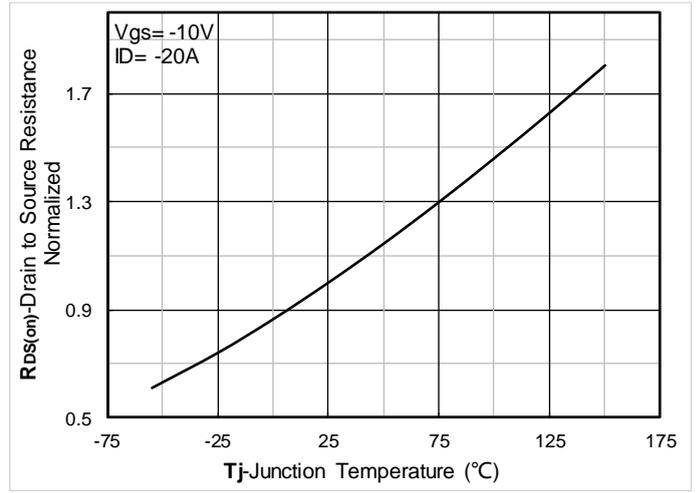


Figure 6. Normalized On-Resistance

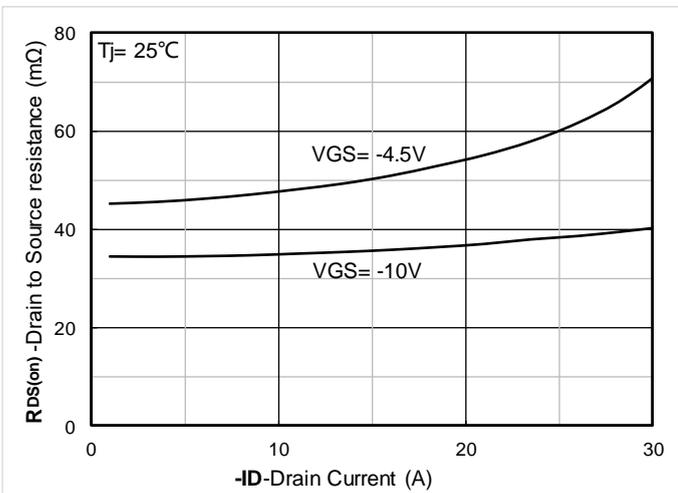


Figure 7. RDS(on) VS Drain Current

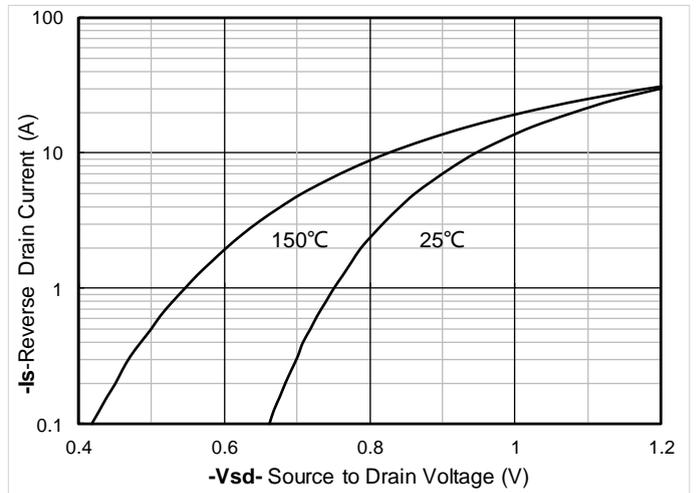


Figure 8. Forward characteristics of reverse diode

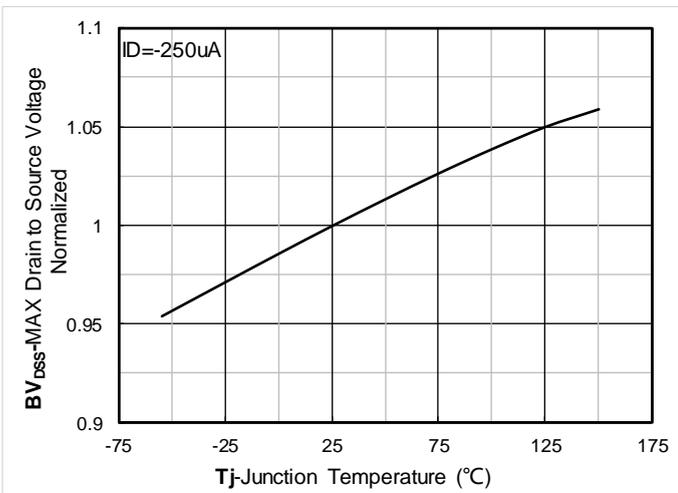


Figure 9. Normalized breakdown voltage

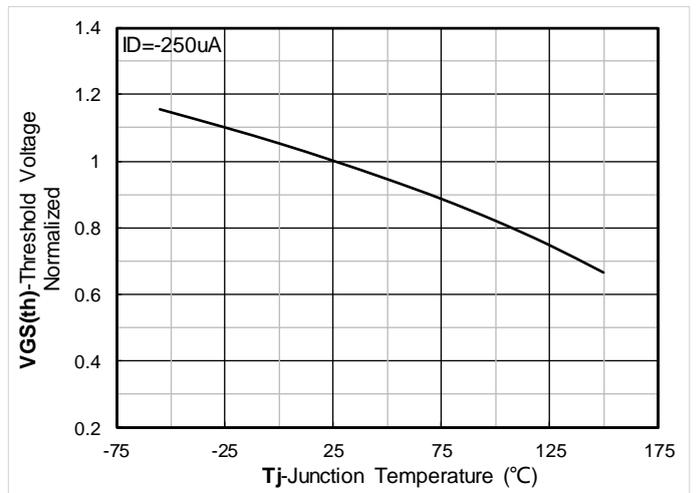


Figure 10. Normalized Threshold voltage



# YJG20NP06A

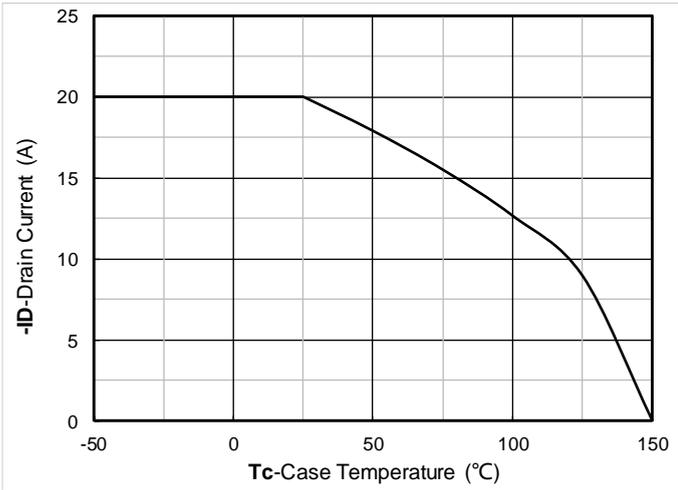


Figure 11. Current dissipation

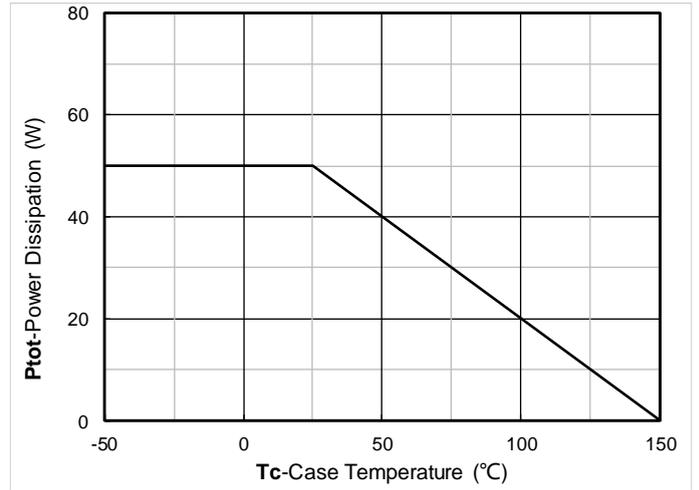


Figure 12. Power dissipation

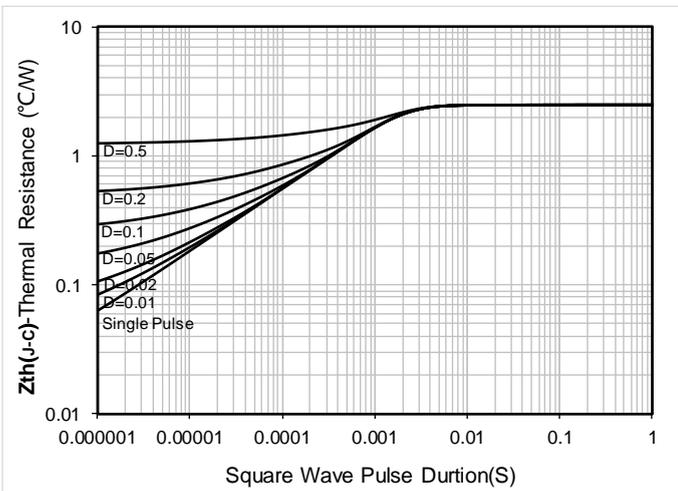


Figure 13. Maximum Transient Thermal Impedance

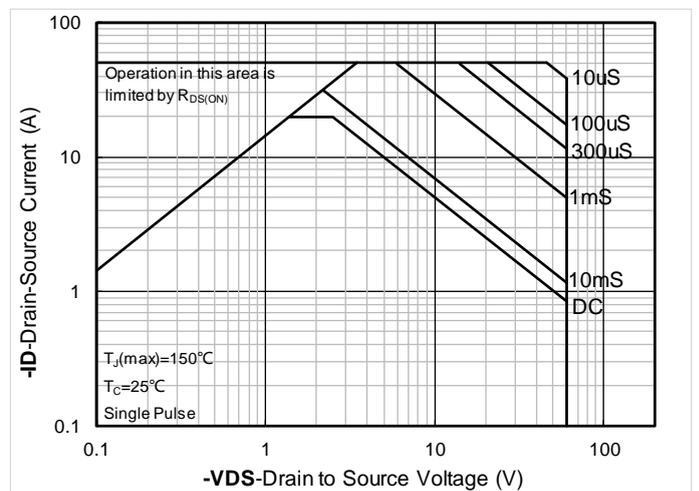
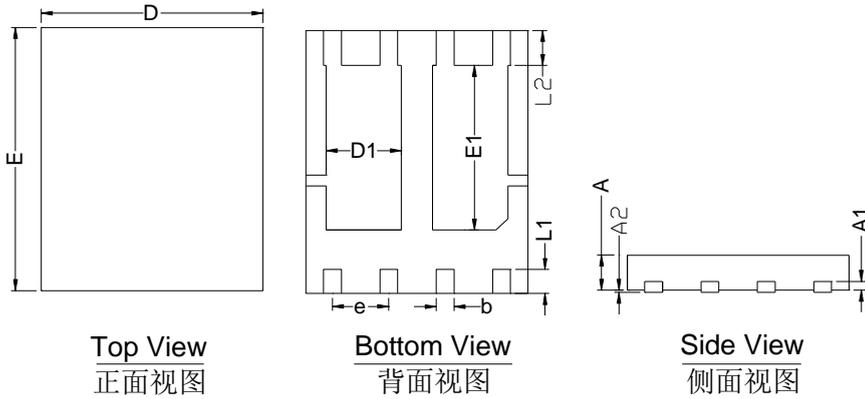


Figure 14. Safe Operation Area

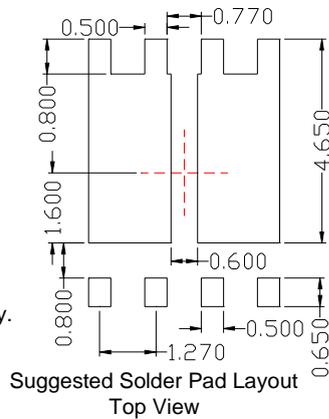


# YJG20NP06A

## DFN5060-8L Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	4.90	5.00	5.10
E	5.90	6.00	6.10
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	1.60	1.70	1.80
E1	3.65	3.75	3.85
L1	0.45	0.55	0.65
L2	0.80 BSC		
b	0.30	0.40	0.50
e	1.27 BSC		



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.10$ mm.
  3. The pad layout is for reference purposes only.



## YJG20NP06A

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